## FLIP CHIP MODULES TEST SPECS

NAND GATE

			#005
TEST	CONDITION	MAX I MUM	MINIMUM
LOWER LEVEL	V <sub>IN</sub> = 0.5 V	3.9 V	3,2 y
LOAD	V = 0.5 V	2,2 MA	1.8 MA
V <sub>CE</sub>	I <sub>C</sub> = 20 MA V <sub>IN</sub> = -2.0V	≦ 300 MV	
INPUT CURRENT		1.1 MA	0.8 MA
TOTAL TRANSITION TIME	RISE	≦ 70 NS	
	FALL	≦ 200 NS	
* ALL UNUSED I	NPUTS ARE BROUGHT	TO -3.0V	

MAINTENANCE INFORMATION

Instruction literature and technical bulletins are available on all digital products, if you would like to be added to our mailing list for this type of material or if you have any questions about the equipment you have purchased, please contact the nearest Digital Sales Office.

Repair of printed circuitry should be done with a low voltage, fairly cool seldering iren to prevent damage to the transisters and keep the capper from lifting. Occillaccapes used to traubisheet a module or system should be

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